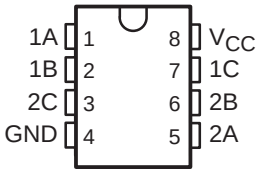
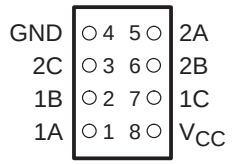
- **Available in the Texas Instruments NanoStar™ and NanoFree™ Packages**
- **Operates at 0.8 V to 2.7 V**
- **Sub 1-V Operable**
- **Max t_{pd} of 0.5 ns at 1.8 V**
- **Low Power Consumption, 10 μA at 2.7 V**
- **High On-Off Output Voltage Ratio**
- **High Degree of Linearity**
- **Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II**
- **ESD Performance Tested Per JESD 22**
  - **2000-V Human-Body Model (A114-B, Class II)**
  - **200-V Machine Model (A115-A)**
  - **1000-V Charged-Device Model (C101)**

DCT OR DCU PACKAGE
(TOP VIEW)



YEP OR YZP PACKAGE
(BOTTOM VIEW)



description/ordering information

This dual analog switch is operational at 0.8-V to 2.7-V V_{CC}, but is designed specifically for 1.1-V to 2.7-V V_{CC} operation.

The SN74AUC2G66 can handle both analog and digital signals. It permits signals with amplitudes of up to 2.7-V (peak) to be transmitted in either direction.

NanoStar™ and NanoFree™ package technology is a major breakthrough in IC packaging concepts, using the die as the package.

Applications include signal gating, chopping, modulation or demodulation (modem), and signal multiplexing for analog-to-digital and digital-to-analog conversion systems.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING‡
−40°C to 85°C	NanoStar™ − WCSP (DSBGA) 0.23-mm Large Bump − YEP	Tape and reel	SN74AUC2G66YEPR	_ _ _U6_
	NanoFree™ − WCSP (DSBGA) 0.23-mm Large Bump − YZP (Pb-free)	Tape and reel	SN74AUC2G66YZPR	
	SSOP − DCT	Tape and reel	SN74AUC2G66DCTR	U66_ _ _
	VSSOP − DCU	Tape and reel	SN74AUC2G66DCUR	U66_

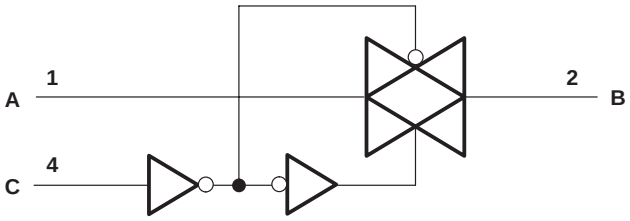
† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

‡ DCT: The actual top-side marking has three additional characters that designate the year, month, and assembly/test site.
DCU: The actual top-side marking has one additional character that designates the assembly/test site.
YEP/YZP: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, ● = Pb-free).

FUNCTION TABLE

CONTROL INPUT (C)	SWITCH
L	OFF
H	ON

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} (see Note 1) . . . . . −0.5 V to 3.6 V
Input voltage range, V_I (see Notes 1 and 2) . . . . . −0.5 V to 3.6 V
Switch I/O voltage range, $V_{I/O}$ (see Notes 1 and 2) . . . . . −0.5 V to V_{CC} + 0.5 V
Control input clamp current, I_{IK} (V_I < 0) . . . . . −50 mA
I/O port diode current, I_{IOK} ($V_{I/O}$ < 0 or $V_{I/O}$ > V_{CC}) . . . . . ±50 mA
On-state switch current, I_T ($V_{I/O}$ = 0 to V_{CC}) . . . . . ±50 mA
Continuous current through V_{CC} or GND . . . . . ±100 mA
Package thermal impedance, θ_{JA} (see Note 3): DCT package . . . . . 220°C/W
DCU package . . . . . 227°C/W
YEP/YZP package . . . . . 102°C/W
Storage temperature range, T_{stg} . . . . . −65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltages are with respect to ground unless otherwise specified.
2. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
V_{CC}	Supply voltage		0.8	2.7	V
V_{IH}	High-level input voltage	V_{CC} = 0.8 V	V_{CC}		V
		V_{CC} = 1.1 V to 1.95 V	$0.65 \times V_{CC}$		
		V_{CC} = 2.3 V to 2.7 V	1.7		
V_{IL}	Low-level input voltage	V_{CC} = 0.8 V		0	V
		V_{CC} = 1.1 V to 1.95 V		$0.35 \times V_{CC}$	
		V_{CC} = 2.3 V to 2.7 V		0.7	
$V_{I/O}$	I/O port voltage		0	V_{CC}	V
V_I	Control input voltage		0	3.6	V
$\Delta t/\Delta v$	Input transition rise or fall rate	V_{CC} = 0.8 V to 1.65 V†		20	ns/V
		V_{CC} = 1.65 V to 2.3 V‡		20	
		V_{CC} = 2.3 V to 2.7 V‡		20	
T_A	Operating free-air temperature		−40	85	°C

† The data was taken at C_L = 15 pF, R_L = 2 kΩ (see Figure 1).
‡ The data was taken at C_L = 30 pF, R_L = 500 Ω (see Figure 1).
NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		V_{CC}	MIN	TYP§	MAX	UNIT
r_{on}	On-state switch resistance	V_I = V_{CC} or GND, V_C = V_{IH} (see Figures 1 and 2)	I_S = 4 mA	1.1 V		17	40	Ω
				1.65 V		7	20	
			I_S = 8 mA	2.3 V		4	15	
$r_{on(p)}$	Peak on resistance	V_I = V_{CC} to GND, V_C = V_{IH} (see Figures 1 and 2)	I_S = 4 mA	1.1 V		131	180	Ω
				1.65 V		32	80	
			I_S = 8 mA	2.3 V		15	20	
Δr_{on}	Difference of on-state resistance between switches	V_I = V_{CC} to GND, V_C = V_{IH} (see Figures 1 and 2)	I_S = 4 mA	1.1 V			3	Ω
				1.65 V			1	
			I_S = 8 mA	2.3 V			1	
$I_{S(off)}$	Off-state switch leakage current	V_I = V_{CC} and V_O = GND, or V_I = GND and V_O = V_{CC}, V_C = V_{IL} (see Figure 3)		2.7 V			±1	µA
							±0.1†	
$I_{S(on)}$	On-state switch leakage current	V_I = V_{CC} or GND, V_C = V_{IH}, V_O = Open (see Figure 4)		2.7 V			±1	µA
							±0.1†	
I_I	Control input current	V_I = V_{CC} or GND		0 to 2.7 V			±5	µA
I_{CC}	Supply current	V_I = V_{CC} or GND,	I_O = 0	0.8 V to 2.7 V			10	µA
C_{ic}	Control input capacitance			2.5 V		2.5		pF
$C_{io(off)}$	Switch input/output capacitance			2.5 V		3		pF
$C_{io(on)}$	Switch input/output capacitance			2.5 V		7		pF

§ T_A = 25°C

switching characteristics over recommended operating free-air temperature range, C_L = 15 pF (unless otherwise noted) (see Figure 5)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 0.8 V	V_{CC} = 1.2 V ± 0.1 V		V_{CC} = 1.5 V ± 0.1 V		V_{CC} = 1.8 V ± 0.15 V			V_{CC} = 2.5 V ± 0.2 V		UNIT
			TYP	MIN	MAX	MIN	MAX	MIN	TYP	MAX	MIN	MAX	
t_{pd}†	A or B	B or A	1		0.6		0.5			0.5		0.4	ns
t_{en}	C	A or B	5	0.5	3	0.5	2.1	0.5	0.9	1.6	0.5	1.4	ns
t_{dis}	C	A or B	5.3	0.5	4	0.5	3	0.5	2.6	3.3	0.5	2.7	ns

† The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance when driven by an ideal voltage source (zero output impedance).

switching characteristics over recommended operating free-air temperature range, C_L = 30 pF (unless otherwise noted) (see Figure 5)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 1.8 V ± 0.15 V			V_{CC} = 2.5 V ± 0.2 V		UNIT
			MIN	TYP	MAX	MIN	MAX	
t_{pd}†	A or B	B or A			0.7		0.7	ns
t_{en}	C	A or B	0.5	1.6	2.7	0.5	2.3	ns
t_{dis}	C	A or B	0.5	2.7	3.4	0.5	2	ns

† The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance when driven by an ideal voltage source (zero output impedance).

analog switch characteristics, T_A = 25°C

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	V_{CC}	TYP	UNIT
Frequency response‡ (switch ON)	A or B	B or A	C_L = 50 pF, R_L = 600 Ω, f_{in} = sine wave (see Figure 6)	0.8 V	101	MHz
				1.1 V	150	
				1.4 V	175	
				1.65 V	250	
				2.3 V	400	
			C_L = 5 pF, R_L = 50 Ω, f_{in} = sine wave (see Figure 6)	0.8 V	450	
				1.1 V	>500	
				1.4 V	>500	
				1.65 V	>500	
				2.3 V	>500	
Crosstalk§ (between switches)	A or B	B or A	C_L = 50 pF, R_L = 600 Ω, f_{in} = 1 MHz (sine wave) (see Figure 7)	0.8 V	−60	dB
				1.1 V	−60	
				1.4 V	−60	
				1.65 V	−60	
				2.3 V	−60	
			C_L = 5 pF, R_L = 50 Ω, f_{in} = 1 MHz (sine wave) (see Figure 7)	0.8 V	−65	
				1.1 V	−65	
				1.4 V	−65	
				1.65 V	−65	
				2.3 V	−65	

‡ Adjust f_{in} voltage to obtain 0 dBm at output. Increase f_{in} frequency until dB meter reads −3 dB.
§ Adjust f_{in} voltage to obtain 0 dBm at input.

analog switch characteristics, T_A = 25°C (continued)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	V_{CC}	TYP	UNIT
Crosstalk (control input to signal output)	C	A or B	C_L = 50 pF, R_L = 600 Ω, f_{in} = 1 MHz (square wave) (see Figure 8)	0.8 V	9	mV
				1.1 V	14	
				1.4 V	15	
				1.65 V	16	
				2.3 V	20	
Feed-through attenuation‡ (switch OFF)	A or B	B or A	C_L = 50 pF, R_L = 600 Ω, f_{in} = 1 MHz (sine wave) (see Figure 9)	0.8 V	−50	dB
				1.1 V	−50	
				1.4 V	−50	
				1.65 V	−50	
				2.3 V	−50	
			C_L = 5 pF, R_L = 50 Ω, f_{in} = 1 MHz (sine wave) (see Figure 9)	0.8 V	−60	
				1.1 V	−60	
				1.4 V	−60	
				1.65 V	−60	
				2.3 V	−60	
Sine-wave distortion	A or B	B or A	C_L = 50 pF, R_L = 10 kΩ, f_{in} = 1 kHz (sine wave) (see Figure 10)	0.8 V	7	%
				1.1 V	0.25 6	
				1.4 V	0.04	
				1.65 V	0.03	
				2.3 V	0.01	
	A or B	B or A	C_L = 50 pF, R_L = 10 kΩ, f_{in} = 10 kHz (sine wave) (see Figure 10)	0.8 V	3.7	
				1.1 V	0.4	
				1.4 V	0.04	
				1.65 V	0.02	
				2.3 V	0.02	

‡ Adjust f_{in} voltage to obtain 0 dBm at input.

operating characteristics, T_A = 25°C

PARAMETER		TEST CONDITIONS	V_{CC} = 0.8 V	V_{CC} = 1.2 V	V_{CC} = 1.5 V	V_{CC} = 1.8 V	V_{CC} = 2.5 V	UNIT
			TYP	TYP	TYP	TYP	TYP	
C_{pd}	Power dissipation capacitance	f = 10 MHz	2.5	2.5	2.5	2.5	2.5	pF

PARAMETER MEASUREMENT INFORMATION

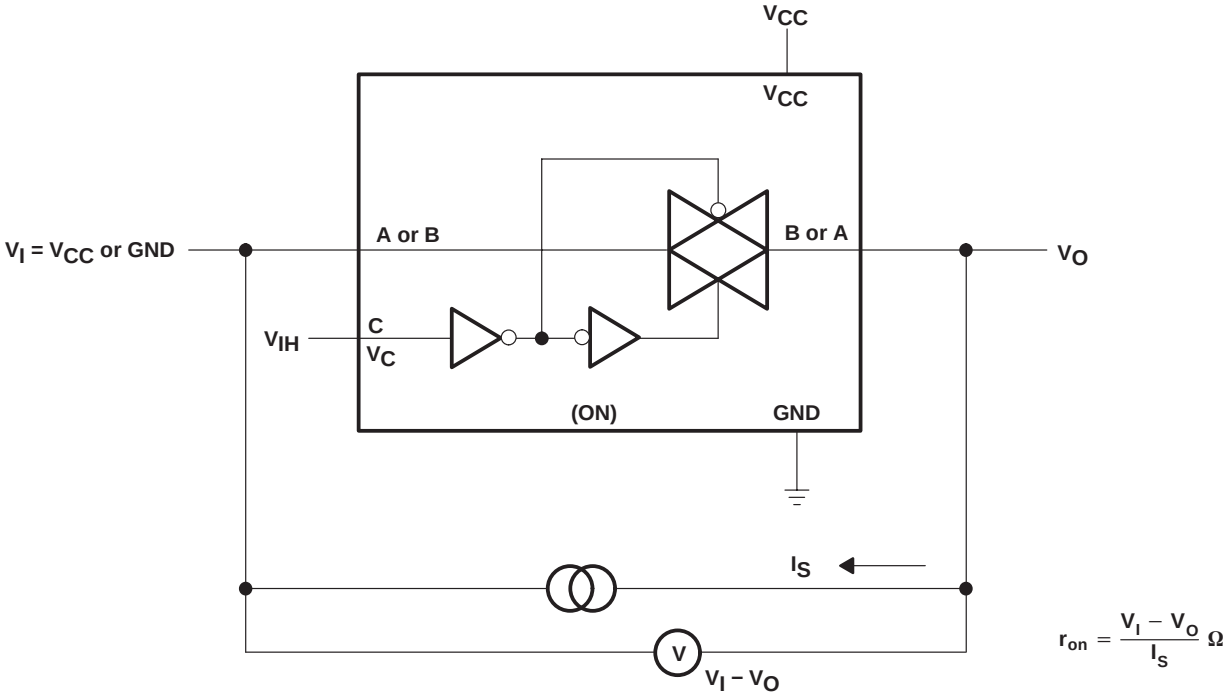


Figure 1. On-State Resistance Test Circuit

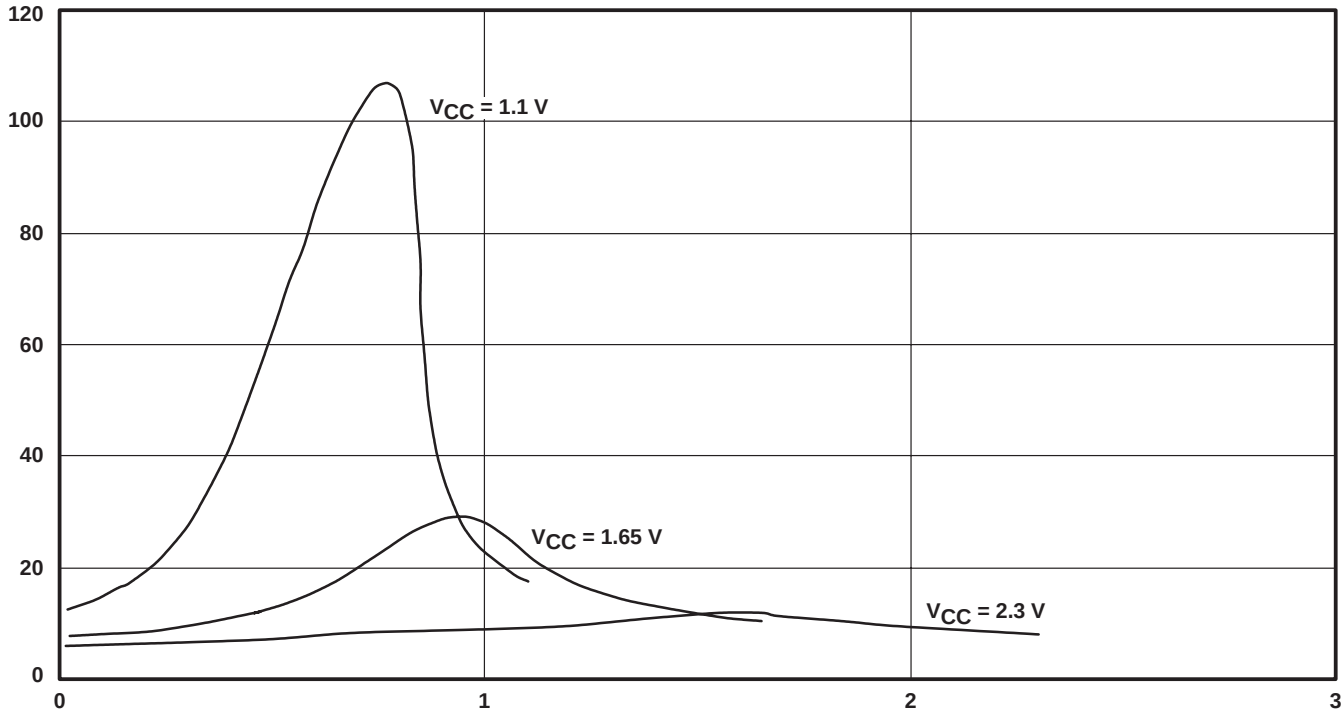


Figure 2. Typical r_{on} as a Function of Voltage (V_I) for V_I = 0 to V_{CC}

PARAMETER MEASUREMENT INFORMATION

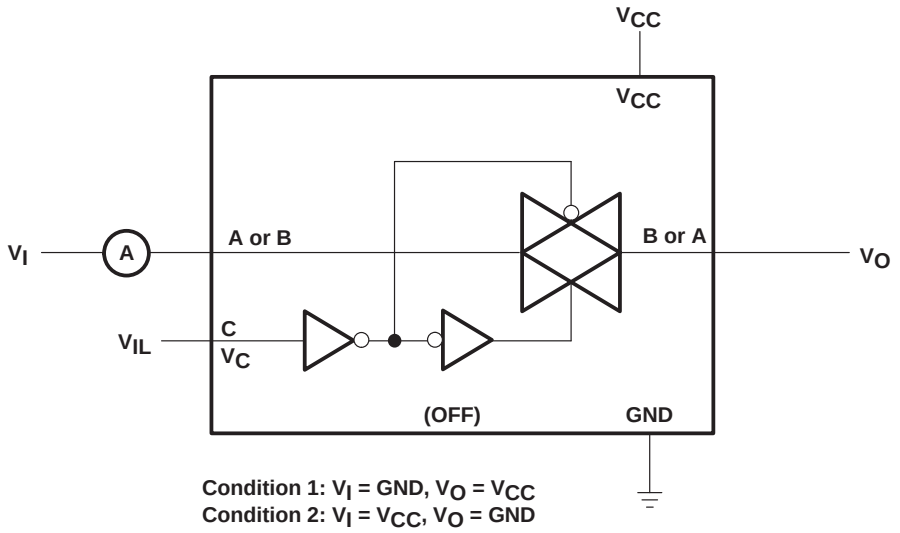


Figure 3. Off-State Switch Leakage-Current Test Circuit

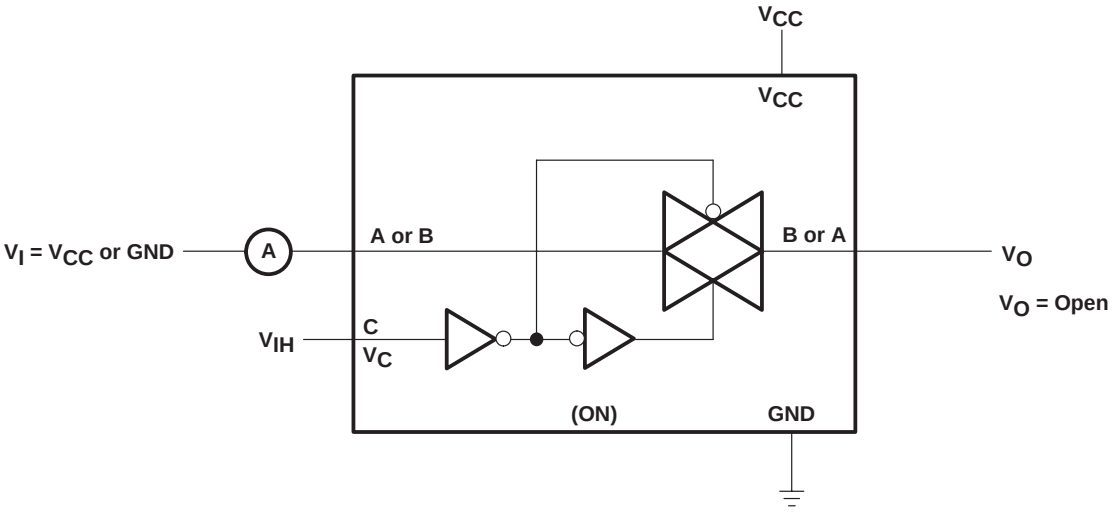
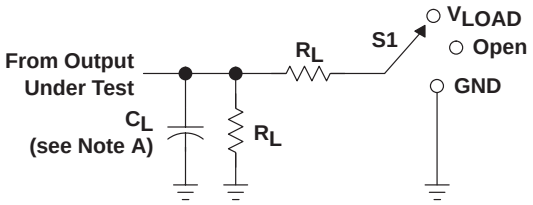


Figure 4. On-State Leakage-Current Test Circuit

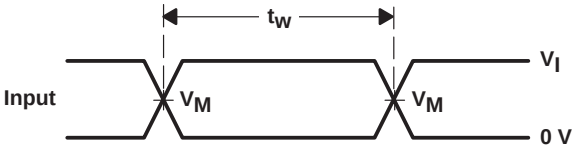
PARAMETER MEASUREMENT INFORMATION



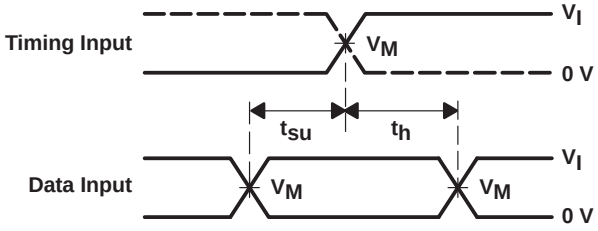
LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	V_{LOAD}
t_{PHZ}/t_{PZH}	GND

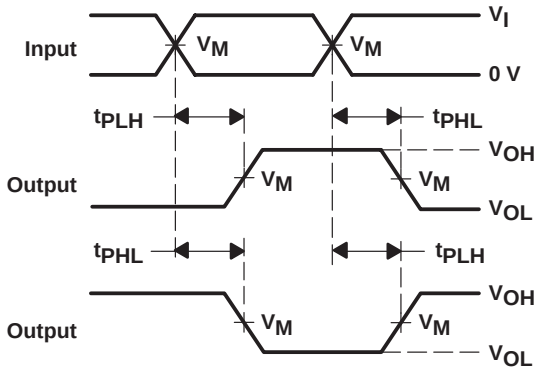
V_{CC}	INPUTS		V_M	V_{LOAD}	C_L	R_L	V_Δ
	V_I	t_r/t_f					
0.8 V	V_{CC}	≤2 ns	$V_{CC}/2$	$2 \times V_{CC}$	15 pF	2 kΩ	0.1 V
1.2 V ± 0.1 V	V_{CC}	≤2 ns	$V_{CC}/2$	$2 \times V_{CC}$	15 pF	2 kΩ	0.1 V
1.5 V ± 0.1 V	V_{CC}	≤2 ns	$V_{CC}/2$	$2 \times V_{CC}$	15 pF	2 kΩ	0.1 V
1.8 V ± 0.15 V	V_{CC}	≤2 ns	$V_{CC}/2$	$2 \times V_{CC}$	15 pF	2 kΩ	0.15 V
2.5 V ± 0.2 V	V_{CC}	≤2 ns	$V_{CC}/2$	$2 \times V_{CC}$	15 pF	2 kΩ	0.15 V
1.8 V ± 0.15 V	V_{CC}	≤2 ns	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	1 kΩ	0.15 V
2.5 V ± 0.2 V	V_{CC}	≤2 ns	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	500 Ω	0.15 V



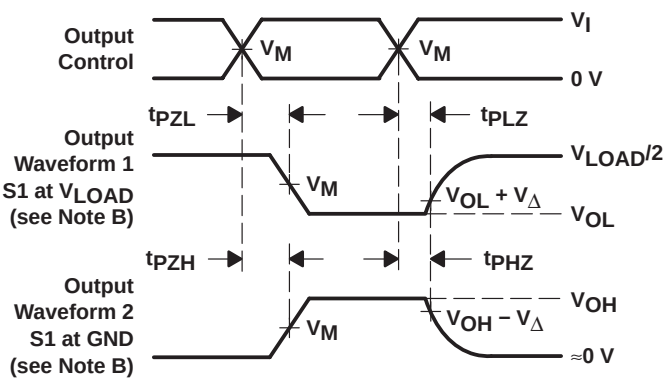
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, slew rate ≥ 1 V/ns.
D. The outputs are measured one at a time with one transition per measurement.
E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
F. t_{PZL} and t_{PZH} are the same as t_{en}.
G. t_{PLH} and t_{PHL} are the same as t_{pd}.
H. All parameters and waveforms are not applicable to all devices.

Figure 5. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION

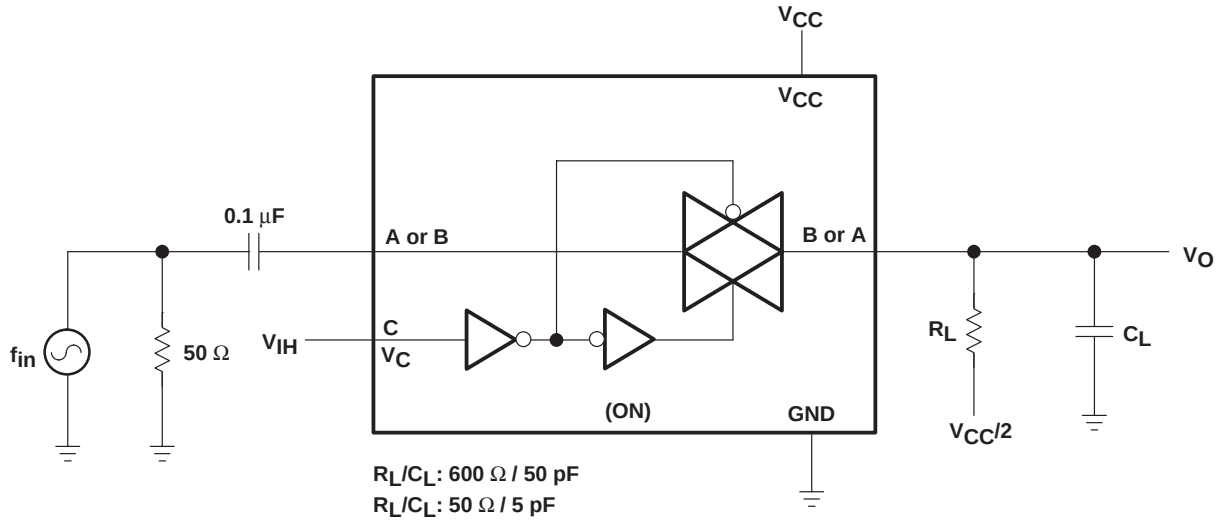


Figure 6. Frequency Response (Switch ON)

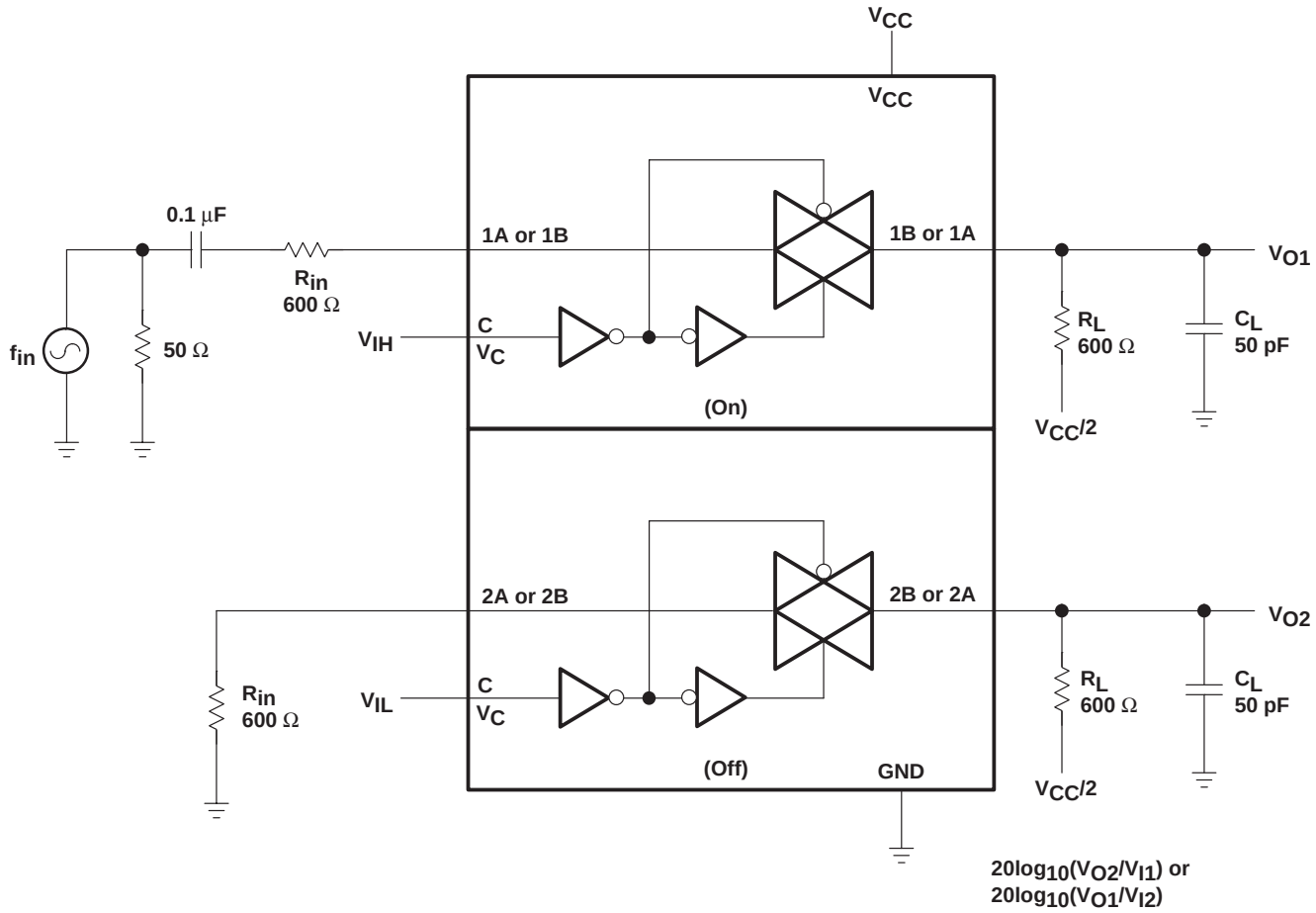


Figure 7. Crosstalk (Between Switches)

PARAMETER MEASUREMENT INFORMATION

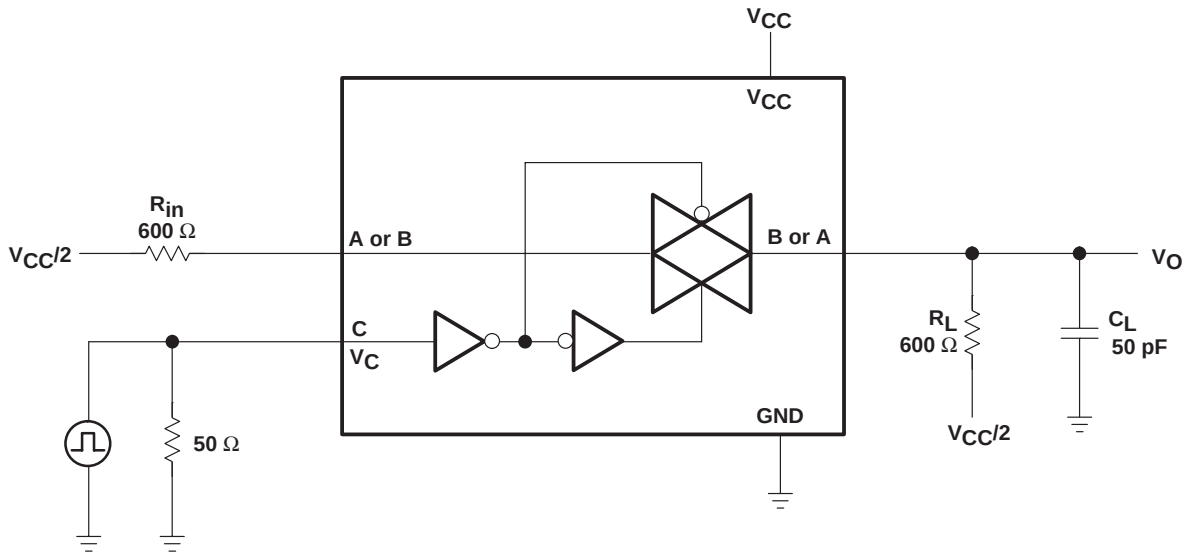


Figure 8. Crosstalk (Control Input − Switch Output)

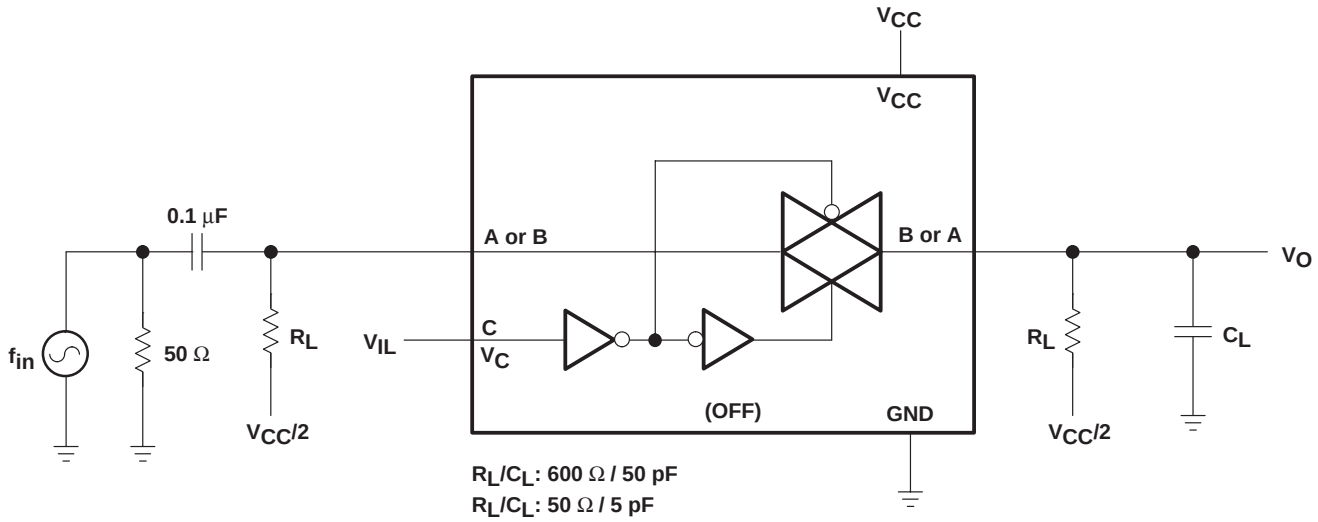
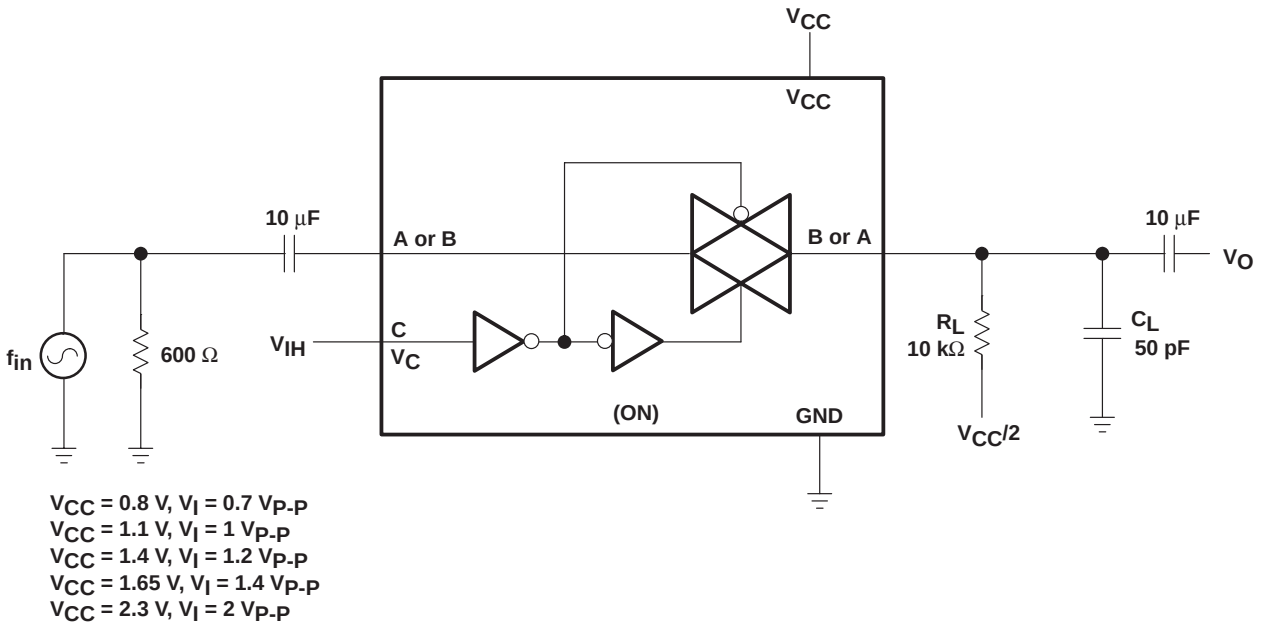


Figure 9. Feed Through, Switch Off

PARAMETER MEASUREMENT INFORMATION

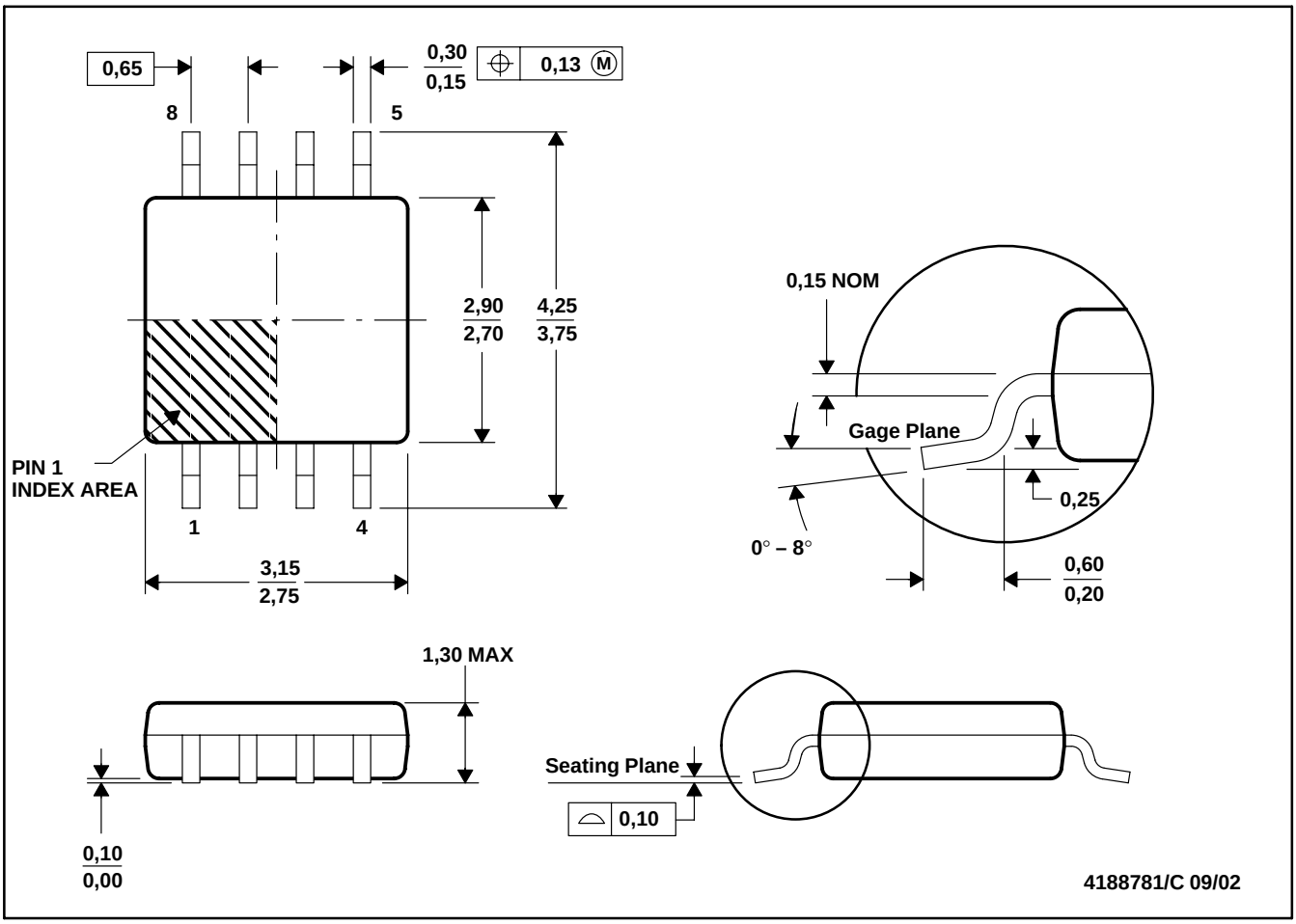


V_{CC} = 0.8 V, V_I = 0.7 V_{P-P}
V_{CC} = 1.1 V, V_I = 1 V_{P-P}
V_{CC} = 1.4 V, V_I = 1.2 V_{P-P}
V_{CC} = 1.65 V, V_I = 1.4 V_{P-P}
V_{CC} = 2.3 V, V_I = 2 V_{P-P}

Figure 10. Sine-Wave Distortion

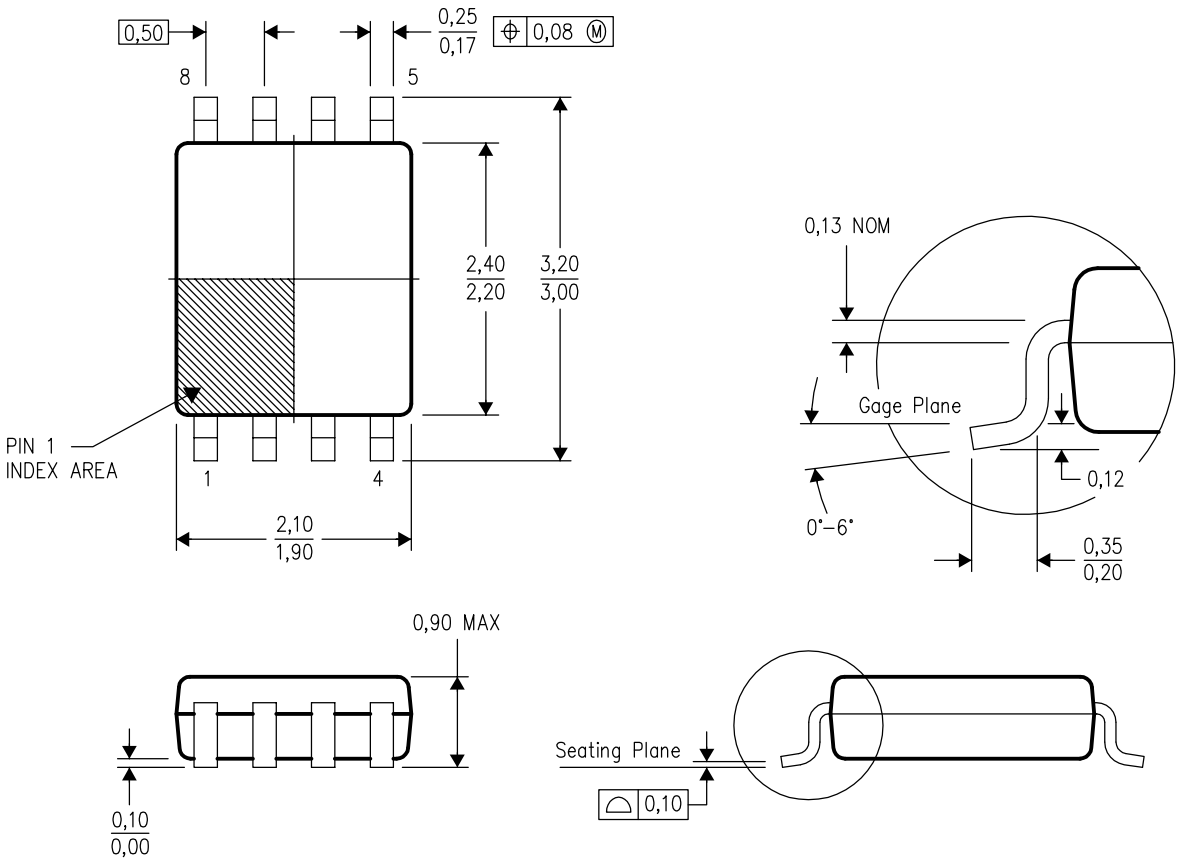
MPDS049B – MAY 1999 – REVISED OCTOBER 2002

DCT (R-PDSO-G8) **PLASTIC SMALL-OUTLINE PACKAGE**



NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion
D. Falls within JEDEC MO-187 variation DA.

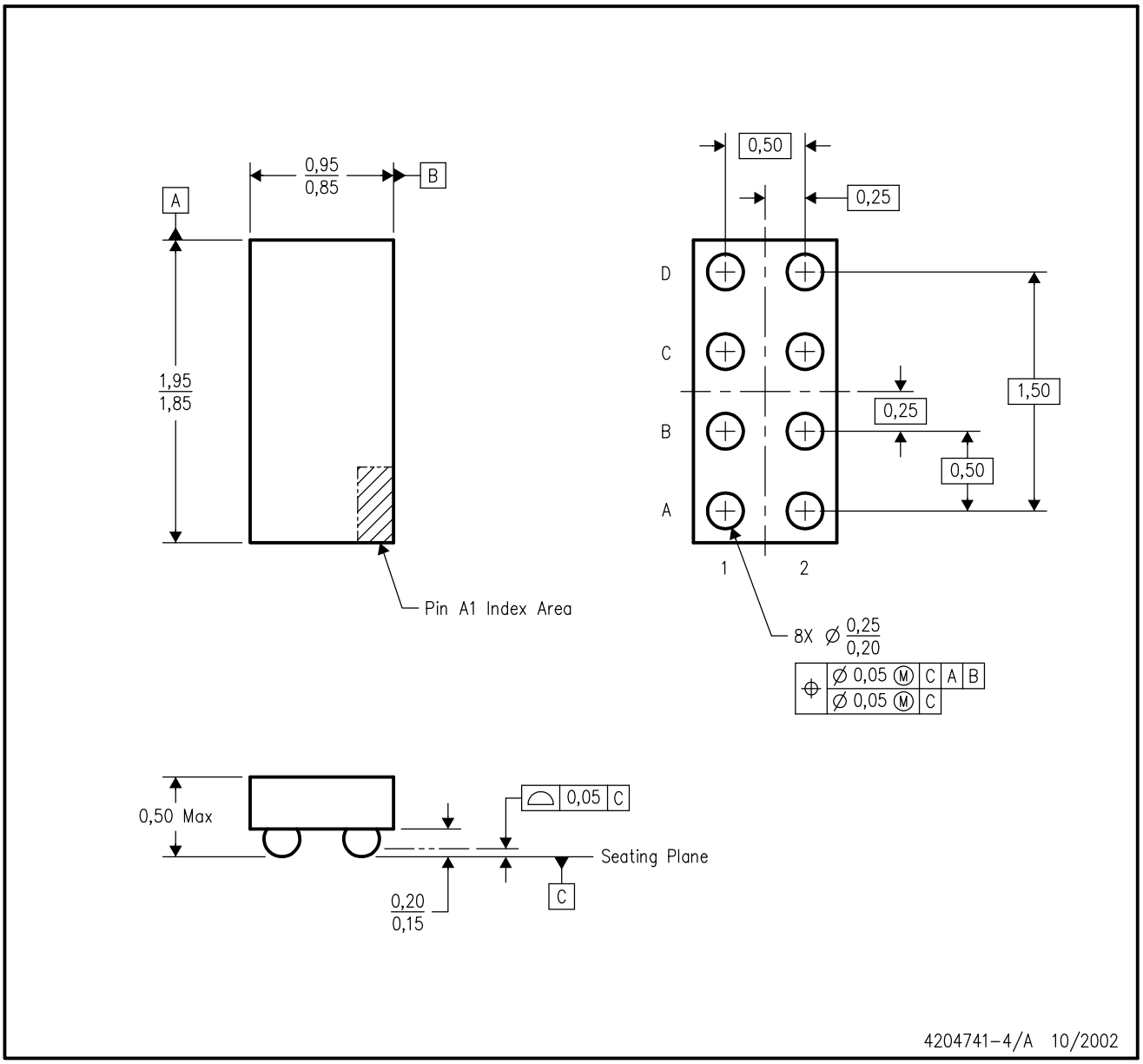
DCU (R–PDSO–G8) PLASTIC SMALL–OUTLINE PACKAGE (DIE DOWN)



4200503/E 05/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion.
D. Falls within JEDEC MO–187 variation CA.

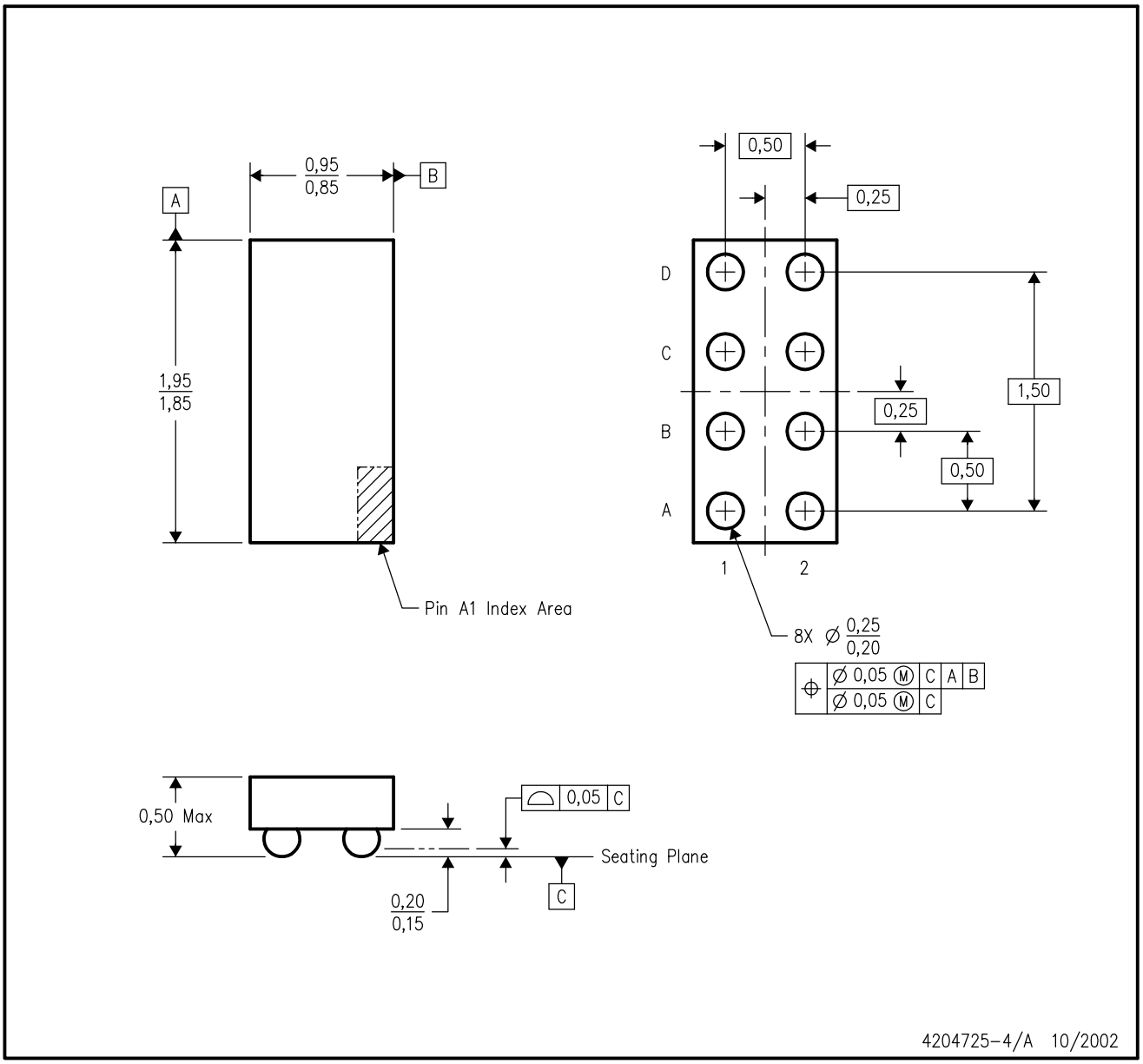
YZP (R–XBGA–N8) DIE–SIZE BALL GRID ARRAY



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. NanoFree™ package configuration.
D. This package is lead–free. Refer to the 8 YEP package (drawing 4204725) for tin–lead (SnPb).

NanoFree is a trademark of Texas Instruments.

YEP (R–XBGA–N8) DIE–SIZE BALL GRID ARRAY



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. NanoStar™ package configuration.
D. This package is tin–lead (SnPb). Refer to the 8 YZP package (drawing 4204741) for lead–free.

NanoStar is a trademark of Texas Instruments.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		**Applications**	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
		Telephony	www.ti.com/telephony
		Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments
Post Office Box 655303 Dallas, Texas 75265